

Amendments to the Claims:

The following listing of claims replaces all prior versions and listings of the claims in this application.

Listing of the Claims:

1.-28. (Cancelled).

29. (Currently Amended) A radiation cured encapsulating material having a tear resistance of less than about 2.20 pounds force and an adhesion force to an underlying surface material of greater than about 0.0044 pounds force.

30. (Currently Amended) A radiation cured encapsulating material as defined by claim 29, having a percent elongation at break of at least about 5% and a modulus at 25°C of at least about 1000 psi.

31. (Currently Amended) A radiation cured encapsulating material as defined by claim 30, having a tear resistance of less than about 1.10 pounds force, a modulus at 25°C in the range of from about 1000 to about 50,000 psi, a percent elongation at break of at least about 10%, and an adhesion force to an underlying surface material of greater than about 0.011 pounds force.

32. (Currently Amended) A radiation cured encapsulating material as defined by claim 30, having a tear resistance of less than about 0.44 pounds force, a modulus at 25°C in the range of from about 3000 to about 25,000 psi, a percent elongation at break of at least about 20%, and an adhesion force to an underlying surface material of greater than about 0.015 pounds force.

33. (Currently Amended) A radiation cured encapsulating material as defined by claim 29, formed by radiation curing a composition comprising from about 30 to about 80 weight percent of a polyether-based urethane acrylate oligomer, from about 1 to about 40 weight percent of isocyanurate monomer having a plurality of acrylate or methacrylate groups, and an effective amount of a photoinitiator for radiation curing the composition upon exposure to curing radiation.

34. (Currently Amended) A radiation cured encapsulating material as defined by claim 33, wherein the polyether-based urethane acrylate oligomer comprises a polypropylene glycol-based urethane acrylate oligomer.

35. (Currently Amended) A radiation cured encapsulating material as defined by claim 33, wherein the isocyanurate monomer comprises a triacrylate of trishydroxyethyl isocyanurate.

36. (Currently Amended) A radiation cured encapsulating material as defined by claim 33, formed by radiation curing a composition comprising from about 40 to about 75 weight percent of the polyether-based urethane acrylate oligomer, from about 10 to about 30 weight percent of the isocyanurate monomer, and from about 0.1 to about 20 weight percent of the photoinitiator.

37. (Currently Amended) A radiation cured encapsulating material as defined by claim 33, formed by radiation curing a composition comprising from about 50 to about 70 weight percent of the polyether-based urethane acrylate oligomer, from about 15 to about 25

weight percent of the isocyanurate monomer, and from about 1 to about 10 weight percent of the photoinitiator.

38. (Currently Amended) A radiation cured encapsulating material as defined by claim 37, wherein the polyether-based urethane acrylate oligomer comprises a polypropylene glycol-based urethane acrylate oligomer and the isocyanurate monomer comprises a triacrylate of trishydroxyethyl isocyanurate.

39. (Currently Amended) A radiation cured encapsulating material as defined by claim 29, having a tear resistance of less than about 1.10 pounds force.

40. (Currently Amended) A radiation cured encapsulating material as defined by claim 29, having a tear resistance of less than about 0.44 pounds force.

41. (Currently Amended) A radiation cured encapsulating material as defined by claim 30, having a modulus at 25°C of at least about 3000 psi.

42. (Currently Amended) A radiation cured encapsulating material as defined by claim 30, having a modulus at 25°C in the range of from about 3000 to about 50,000 psi.

43. (Currently Amended) A radiation cured encapsulating material as defined by claim 30, having a modulus at 25°C in the range of from about 3000 to about 25,000 psi.

44. (Currently Amended) A radiation cured encapsulating material as defined by claim 29, having a percent elongation at break of at least about 5%.

45. (Currently Amended) A radiation cured encapsulating material as defined by claim 29, having a percent elongation at break of at least about 10%.

46. (Currently Amended) A radiation cured encapsulating material as defined by claim 29, having a percent elongation at break of at least about 20%.

47. (Currently Amended) A radiation cured encapsulating material as defined by claim 29, having a tear resistance of less than about 1.10 pounds force, a modulus at 25°C of at least about 3000 psi, and a percent elongation at break of at least about 10%.

48. (Currently Amended) A radiation cured encapsulating material as defined by claim 29, having a tear resistance of less than about 0.44 pounds force, a modulus at 25°C in the range of from about 3000 to about 15,000 psi, and a percent elongation at break of at least about 20%.

49. (Currently Amended) A radiation cured encapsulating material as defined by claim 33, wherein the composition further comprises a viscosity-reducing component in an amount sufficient to lower the viscosity of the composition.

50. (Currently Amended) A radiation cured encapsulating material as defined by claim 33, wherein the composition further comprises a coefficient of friction reducing component in an amount sufficient to lower the coefficient of friction of the radiation cured material.

51. (New) A radiation cured encapsulating material having a tear resistance of less than about 2.20 pounds force, an adhesion force to an underlying surface material of greater than about 0.0044 pounds force, and a modulus at 25°C of from about 3000 to about 50,000 psi.

52. (New) A radiation cured encapsulating material as defined by claim 51, wherein the modulus at 25°C is from about 3000 to about 25,000 psi.